



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re application of :
Hironori OSUGA :
Serial No. 10/808,483 : Group Art Unit: 1712
Filed: March 25, 2004 : Examiner: R. Sellers

For: EPOXY RESIN COMPOSITION
AND SEMICONDUCTOR
APPARATUS :
:

D E C L A R A T I O N

Commissioner for Patents
Alexandria VA 22313-1450

Sir:

I, Shigeyuki MAEDA, declare that I am a citizen of Japan, residing Utsunomiya-shi, Tochigi, Japan, declare:

That I graduated from Department of Applied Chemistry, Faculty of Engineering, Utsunomiya University in March 1993.

That I entered SUMITOMO BAKELITE Co., Ltd. in April 1993, and was engaged in the study of flexible printed circuits from 1993 to 1995, and since 1995, have been engaged in the study of epoxy molding compounds.

That I am familiar with the present invention and the prosecution history of the present application.

That I have carried out the following experiments in order to demonstrate the unexpected superiority of the invention of the above-identified application to the prior art references.

I. Experiment

The same procedures as in Example 2 of the present application were repeated except that the amounts of the components were changed as shown in Table II below with the amount of the o-cresol novolak epoxy resin and phenolic novolak resin being kept at a constant value, and soldering resistance was evaluated as follows.

In the same manner as in the measurement of warpage of package, a 225 pBGA was molded, and this was post-cured at 175°C for 2 hours to obtain 10 samples, each. Each 10 samples were subjected to treatment at a temperature of 60°C and a relative humidity of 60% for 120 hours, and then subjected to an IR reflow treatment wherein peak temperature was 260°C and temperatures not lower than 255°C was maintained for 10 seconds. Occurrence of delamination and cracking inside the package was examined by an ultrasonic detector. When the number of rejected packages in which cracking and delamination were observed was n, this is shown by n/10.

Table II

	Additional Experiment				
	6	7	8	9	10
O-Cresol novolak epoxy resin	5.3	5.3	5.3	5.3	5.3
Phenolic novolak resin	2.7	2.7	2.7	2.7	2.7
Spherical alumina 1	90.0	61.5	101.0	45.7	190.0
Ultrafine silica 1 (specific surface area 180 m^2/g)	0.5	0.5	0.5	0.5	0.5
Polyorganosiloxane represented by the formula (1)	1.0	1.0	1.0	1.0	1.0
Triphenylphosphine	0.1	0.1	0.1	0.1	0.1
Carbon black	0.2	0.2	0.2	0.2	0.2
Carnauba wax	0.2	0.2	0.2	0.2	0.2
Spiral flow (cm)	130	165	119	185	38
Thermal conductivity (W/mK)	3.5	3.1	3.6	2.6	4.0
Warpage of package (μm)	80	96	72	140	*
Length of flash (mm)	<1.0	1.4	<1.0	3.5	*
Temperature cycle property: The number of rejected packages after 500 cycles	0/10	1/10	0/10	10/10	*
Temperature cycle property: The number of rejected packages after 1000 cycles	1/10	4/10	0/10	10/10	*
Solder resistance: The number of rejected packages	0/10	1/10	0/10	8/10	*

*: immeasurable because of failure in being charged into the mold

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II. Results

The above table and Table I of the declaration filed on February 26, 2007 clearly show that the claimed amount of the spherical alumina is critical with respect to the thermal conductivity, warpage of package, length of flash, temperature cycle property and soldering resistance even when the amount of the o-cresol novolak epoxy resin and phenolic novolak resin is kept at a constant value. Thus, the present invention attains superiority which cannot be expected from the prior art references, and hence is patentable thereover.

The undersigned declarant declares further that all statements made herein of own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed this 6th day of August 2007.

S. Maeda

Shigeyuki MAEDA